

1. A sensor module, comprising:
  - (a) a housing having at least one interior wall surface;
  - (b) a CCD sensor unit disposed at least partially within said housing, and
  - 5 (c) a plate-like carrier unit disposed between said wall surface and said sensor unit.
2. A sensor module as claimed in claim 1, wherein said plate-like carrier unit has a thermal expansion coefficient  
10 which substantially equals the thermal expansion of said CCD sensor unit.
3. A sensor module as claimed in claim 1, wherein said plate-like carrier unit is formed, at least in part, of alumi-  
15 num nitride (AlN).
4. A sensor module as claimed in claim 3, wherein said plate-like carrier unit is fixed to said housing by means of a quasi-punctiform connection.  
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5. A sensor module as claimed in claim 1, wherein said carrier unit is fixed to said housing by at least one of, an adhesively bonded joint, and a soldered joint.
- 25 6. A sensor module as claimed in one of claim 1, further comprising a gap formed between said carrier unit and said housing.
7. A sensor module as claimed in claim 1, wherein said CCD  
30 sensor unit is fixed to said carrier unit by at least one of, an adhesively bonded joint, and a soldered joint.

8. A sensor module as claimed in claim 1, wherein said housing further includes a glass plate.

5 9. A sensor module as claimed in claim 8, wherein said glass plate hermetically seals the interior of said housing.

10 10. A sensor module as claimed in claim 8, wherein the respective coefficients of thermal expansion of said glass plate and said housing differ by less than  $5 \times 10^{-6} \text{ } ^\circ\text{K}^{-1}$ .

11. A sensor module as claimed in claim 1, wherein the housing comprises a PGA housing.

15 12. A sensor module as claimed in claim 1, wherein at least a portion of said housing is formed of  $\text{Al}_2\text{O}_3$ .